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Vishay Siliconix

Automotive P-Channel 60 V (D-S) 175 °C MOSFET

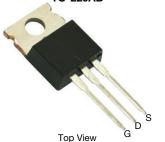
PRODUCT SUMMARY		
V _{DS} (V)	-60	
$R_{DS(on)}$ (Ω) at V_{GS} = -10 V	0.0093	
$R_{DS(on)}$ (Ω) at $V_{GS} = -4.5 \text{ V}$	0.0133	
I _D (A)	-100	
Configuration	Single	

TO-220AB

FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- AEC-Q101 qualified d
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





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			D	

P-Channel MOSFET

ORDERING INFORMATION	
Package	TO-220
Lead (Pb)-free and Halogen-free	SQP100P06-9m3L-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	-60	.,	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Durin Comment	T _C = 25 °C	1	-100		
Continuous Drain Current	T _C = 125 °C	I _D	-58		
Continuous Source Current (Diode Conduction) ^a		I _S	-120	Α	
Pulsed Drain Current b		I _{DM}	-300		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	-70		
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	245	mJ	
Marian In December Disable at the	T _C = 25 °C	P _D	187	W	
Maximum Power Dissipation ^b	T _C = 125 °C	- FD	62	VV	
Operating Junction and Storage Temperature	re Range	T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount c	R_{thJA}	40	°C/W
Junction-to-Case (Drain)		R_{thJC}	0.8	C/VV

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square Pcb (Fr-4 material).
- d. Parametric verification ongoing.

S14-2075-Rev. A, 03-Nov-14



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA		-60	-	-	.,,
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = -250 μA	-1.5	-2.0	-2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = -60 V	-	-	-1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = -60 V, T _J = 125 °C	-	-	-50	μΑ
		V _{GS} = 0 V	V _{DS} = -60 V, T _J = 175 °C	-	-	-250	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = -10 V	V _{DS} ≤ -5 V	-100	-	=	Α
		V _{GS} = -10 V	I _D = -30 A	-	0.0072	0.0093	Ω
David On the On Olate Basistana 3	В	V _{GS} = -10 V	I _D = -30 A, T _J = 125 °C	-	-	0.0151	
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = -10 V	I _D = -30 A, T _J = 175 °C	-	-	0.0184	
		V _{GS} = -4.5 V	I _D = -20 A	-	0.0102	0.0133	
Forward Transconductance b	9 _{fs}	V _{DS} =	V _{DS} = -15 V, I _D = -30 A		82	-	S
Dynamic ^b		<u>.</u>					
Input Capacitance	C _{iss}			-	9605	12 010	
Output Capacitance	Coss	V _{GS} = 0 V	V _{DS} = -25 V, f = 1 MHz	-	1030	1290	pF
Reverse Transfer Capacitance	C _{rss}	1		-	750	940	
Total Gate Charge °	Qg			-	198	300	
Gate-Source Charge ^c	Q_{gs}	V _{GS} = -10 V	$V_{DS} = -30 \text{ V}, I_{D} = -100 \text{ A}$	-	30	-	nC
Gate-Drain Charge ^c	Q _{gd}	1		-	54	-	
Gate Resistance	R_{g}		f = 1 MHz	1	2.2	3.5	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	18	30	
Rise Time ^c	t _r	V_{DD} = -30 V, R_L = 0.3 Ω $I_D \cong$ -100 A, V_{GEN} = -10 V, R_g = 1 Ω		-	12	20	
Turn-Off Delay Time ^c	t _{d(off)}			-	85	130	ns
Fall Time ^c	t _f			-	36	55	1
Source-Drain Diode Ratings and Chara	acteristics ^b						
Pulsed Current a	I _{SM}			-		-300	А
Forward Voltage	V _{SD}	I _F =	I _F = -80 A, V _{GS} = 0		-0.95	-1.5	V
	1						

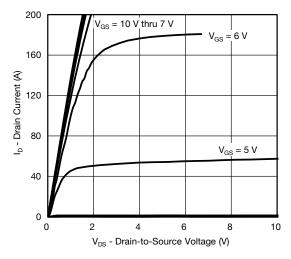
Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

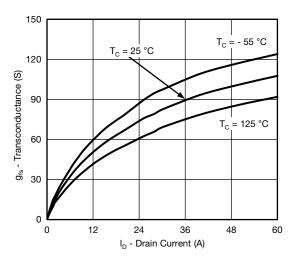
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



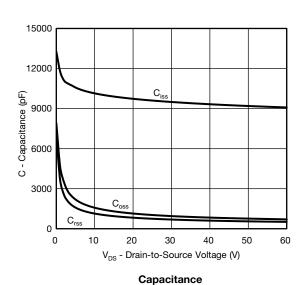
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

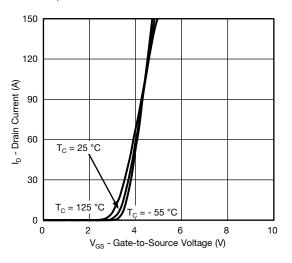


Output Characteristics

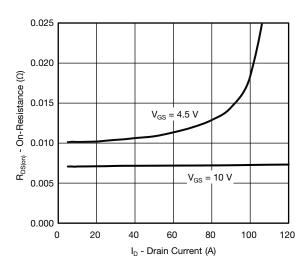


Transconductance

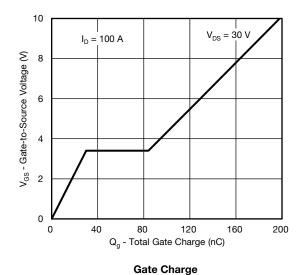




Transfer Characteristics

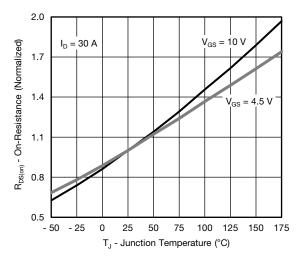


On-Resistance vs. Drain Current

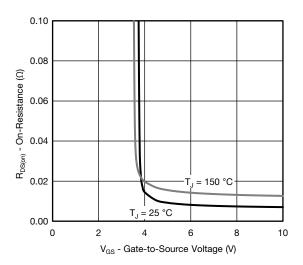




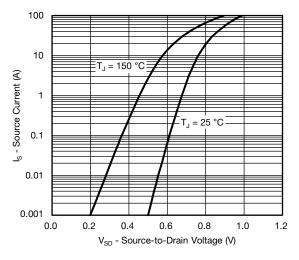
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



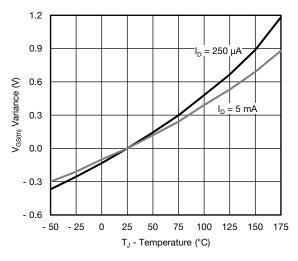
On-Resistance vs. Junction Temperature



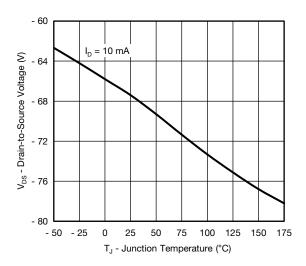
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



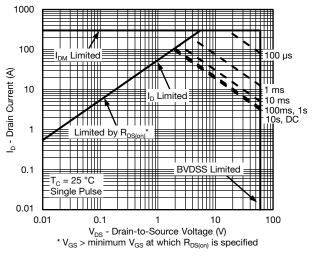
Threshold Voltage



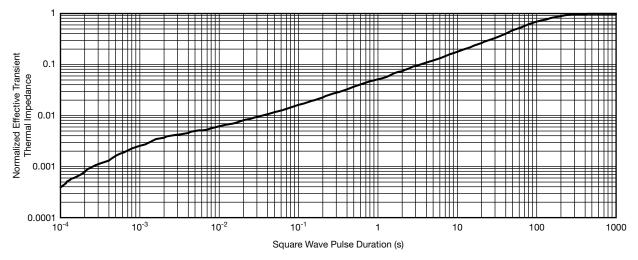
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



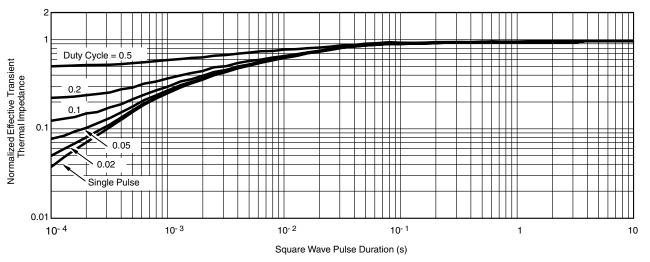
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62971.



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TO-220AB



	D2

	MILLIMETERS		INC	NCHES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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